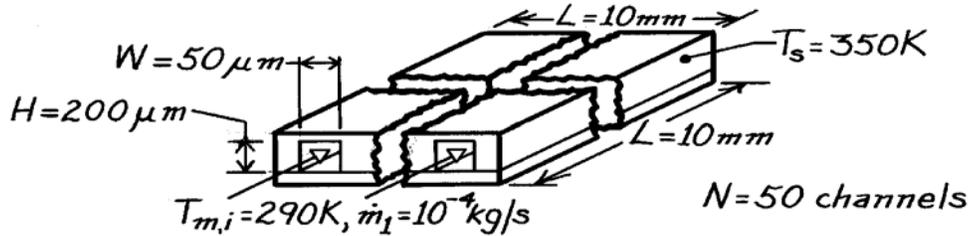


### PROBLEM 8.107

**KNOWN:** Chip and cooling channel dimensions. Channel flowrate and inlet temperature. Chip temperature.

**FIND:** Water outlet temperature and chip power.

**SCHEMATIC:**



**ASSUMPTIONS:** (1) Incompressible liquid with negligible viscous dissipation, (2) Uniform channel surface temperature, (3)  $\bar{T}_m = 300\text{ K}$ , (4) Fully developed flow.

**PROPERTIES:** Table A-6, Water ( $\bar{T}_m = 300\text{ K}$ ):  $c_p = 4179\text{ J/kg}\cdot\text{K}$ ,  $\mu = 855 \times 10^{-6}\text{ kg/s}\cdot\text{m}$ ,  $k = 0.613\text{ W/m}\cdot\text{K}$ ,  $\text{Pr} = 5.83$ .

**ANALYSIS:** Using the hydraulic diameter, find the Reynolds number,

$$D_h = \frac{4(H \times W)}{2(H + W)} = \frac{2(50 \times 200)\ \mu\text{m}^2}{250\ \mu\text{m}} 10^{-6}\text{ m}/\mu\text{m} = 8 \times 10^{-5}\text{ m}$$

$$\text{Re}_D = \frac{\rho u_m D_h}{\mu} = \frac{\dot{m}_1 D_h}{A_c \mu} = \frac{10^{-4}\text{ kg/s} (8 \times 10^{-5}\text{ m})}{(50 \times 200) 10^{-12}\text{ m}^2 (855 \times 10^{-6}\text{ kg/s}\cdot\text{m})} = 936.$$

Hence, the flow is laminar and, from Table 8.1,  $\text{Nu}_D = 4.44$ , so that

$$h = \text{Nu}_D \frac{k}{D_h} = \frac{4.44(0.613\text{ W/m}\cdot\text{K})}{8 \times 10^{-5}\text{ m}} = 34,022\text{ W/m}^2 \cdot \text{K}.$$

With  $P = 2(H + W) = 2(250\ \mu\text{m}) 10^{-6}\text{ m}/\mu\text{m} = 5 \times 10^{-4}\text{ m}$ , Eq. 8.41b yields

$$\frac{T_s - T_{m,o}}{T_s - T_{m,i}} = \frac{350\text{ K} - T_{m,o}}{60\text{ K}} = \exp\left(-\frac{PL}{\dot{m}_1 c_p} h\right) = \exp\left(-\frac{5 \times 10^{-6}\text{ m}^2 \times 34,022\text{ W/m}^2 \cdot \text{K}}{10^{-4}\text{ kg/s} \times 4179\text{ J/kg}\cdot\text{K}}\right)$$

$$T_{m,o} = 350\text{ K} - 60\text{ K} \exp(-0.407) = 310\text{ K}. \quad <$$

Hence, from Eq. 8.34,

$$q = \dot{m} c_p (T_{m,o} - T_{m,i}) = N \dot{m}_1 c_p (T_{m,o} - T_{m,i}) = 50 \times 10^{-4}\text{ kg/s} (4179\text{ J/kg}\cdot\text{K})(20\text{ K}) = 418\text{ W}. \quad <$$

**COMMENTS:** (1) The chip heat flux of  $418\text{ W/cm}^2$  is extremely large and the method provides a very efficient means of heat removal from high power chips. However, clogging of the microchannels is a potential problem which could seriously compromise reliability. (2)  $L/D_h = 125$  and  $0.05\text{ Re}_D \text{Pr} = 272$ . Hence, fully developed conditions are not realized and  $\bar{h} > 34,022$ . The actual power dissipation is therefore greater than  $418\text{ W}$ .